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Principles of Power Integrity for PDN Design

Robust and Cost Effective Design for High Speed Digital Products

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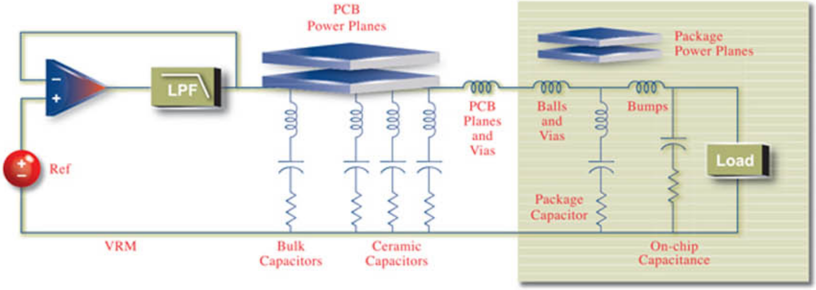

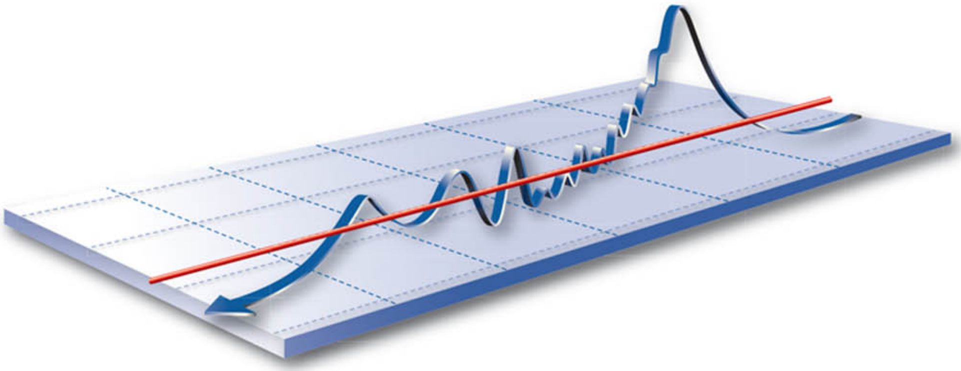

Larry D. Smith • Eric Bogatin

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PRINCIPLES OF POWER INTEGRITY FOR PDN DESIGN— SIMPLIFIED

Principles of Power Integrity for PDN Design--Simplified: Robust and Cost Effective Design for High Speed Digital Products

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